

fischer elektronik

to cool to protect to connect

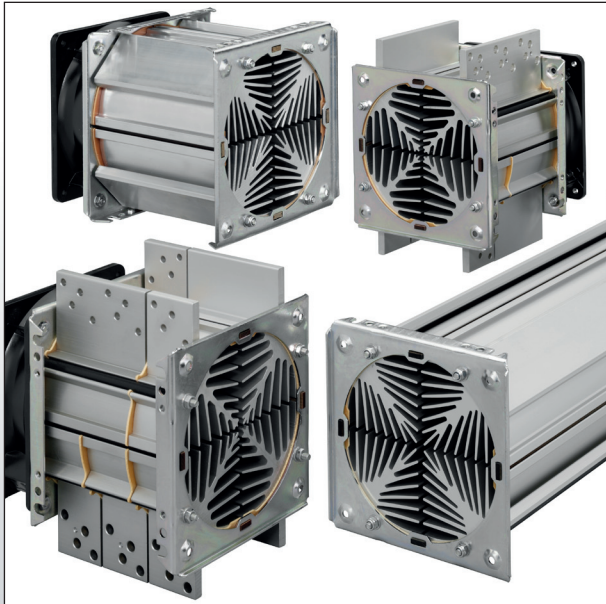


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Germany



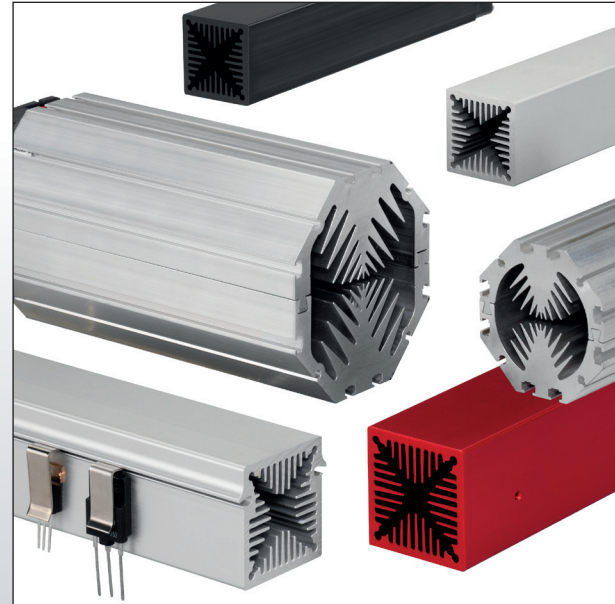
 ISO 9001
ISO 14001
ISO 27001

Segment-, miniature- and high capacity cooling aggregates



Segment cooling aggregates

- modular assembly consisting of different circle- and length segments
- electrical and thermal isolation of the single cooling segment sections
- standard drilling patterns TO 3 and pressfit
- segment profile also sold by the meter
- other fan types and fan voltages upon request



Miniature cooling aggregates

- compact construction for dissipating high power losses on smallest installation space
- heatsink geometries and fixed lengths optimal adjusted to the fan being used; - homogeneous heat dissipation
- mounting of the semi-conductor by means of sliding nut channels or specific snap-to-retaining springs for transistors



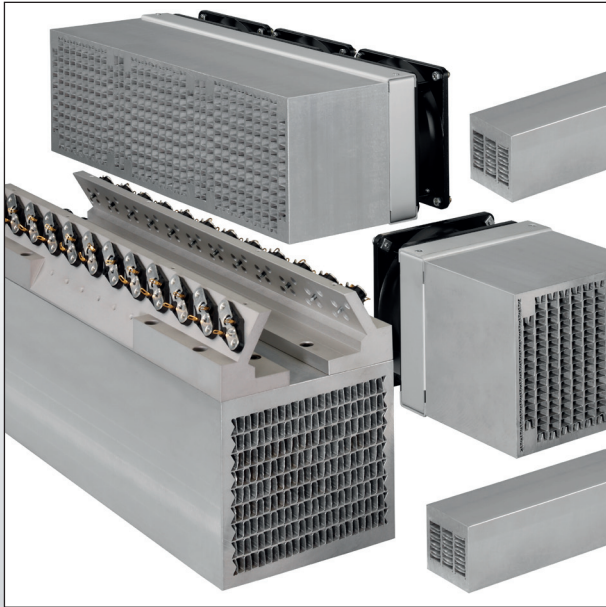
Heatsink cooling aggregates

- effective heat dissipation of high capacity transistors
- very good thermal efficiency in connection with powerful axial fans
- fixing of the heatsink profiles and mounting of the fans by stable endplates
- cooling aggregates are also available without fan
- customer specific treatments according to drawing



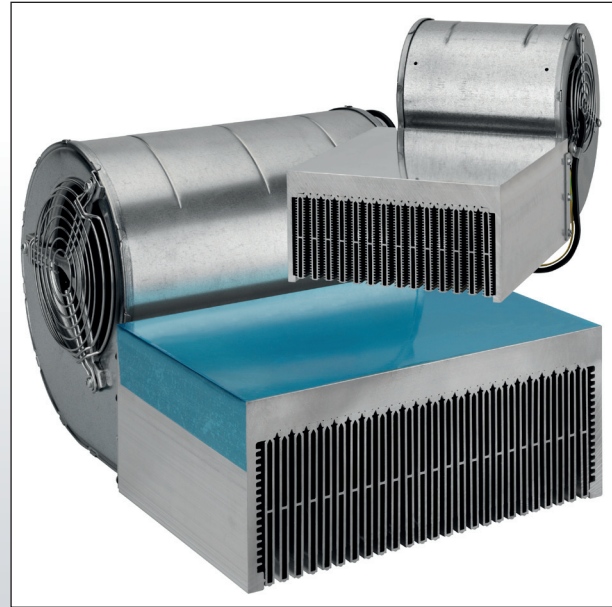
Hollow fin cooling aggregate

- flow-optimized hollow fin geometry
- precise milled flat semi-conductor mounting surface, single- and double-sided
- laminar airflow and noise reduction by means of harmonized chamber systems
- additional treatments, modifications and designs according to customer specifications



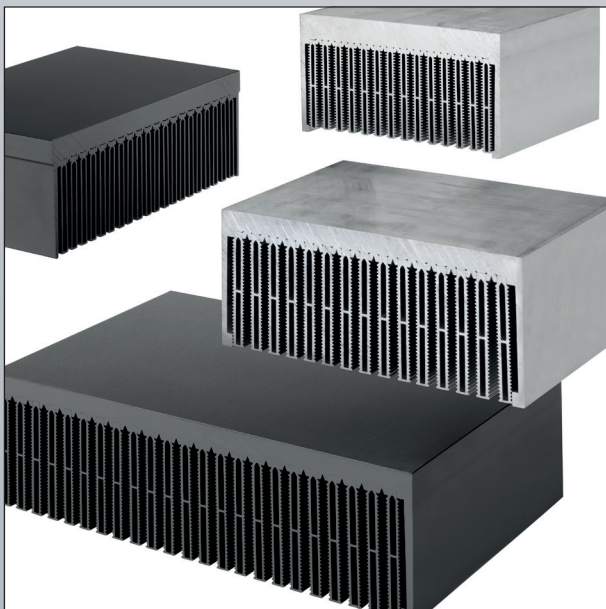
Lamella cooling aggregates

- high power density by big heat exchanging surfaces, thick multi-wall sheets for best heat dissipation
- special formed lamella structures made of aluminium for maximum heat flow
- compact design, very low flow loss
- available with or without airflow chamber systems
- special solutions according to your demand



High capacity cooling aggregates

- very good thermal efficiency
- flow-optimized design with radial fans
- radial fans up to 1310 m³/h
- precise milled flat bottom area for component assembly
- optional motor capacitors
- cooling profile also available without fan
- cover plates for the fin side upon request



High capacity cooling aggregates

- exclusive for forced convection
- for radial- and tangential fans
- flow-optimized design, best heat dissipation by means of especially thick bottom plates
- precise milled flat semi-conductor mounting surfaces
- mechanical treatments, special designs and surface coating for your application



Customer specific treatments

- mechanical treatment possibilities such as cutting, milling, drilling, threading and deburring
- adhesive protection foils avoid scratching of the milled flat semiconductor mounting surfaces
- assembly and packaging of the cooling aggregates upon customer request
- surface treatments according to your demand

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